

# LOW CAPACITANCE STEERING DIODE & TVS ARRAYS

#### **APPLICATIONS**

- ✓ Ethernet 10/100 Base T
- ✔ Computer I/O Ports- SCSI, FireWire & USB
- ✓ Set Top Box Protection

## IEC COMPATIBILITY (EN61000-4)

- ✓ 61000-4-2 (ESD): Air 15kv, Contact 8kv
- √ 61000-4-4 (EFT): 40A 5/50ns
- ✓ 61000-4-5 (Surge): 24A, 8/20µs Level 2(Line-Gnd) & Level 3(Line-Line)

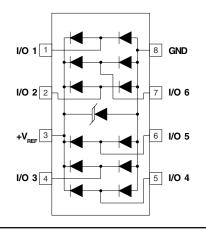
#### **FEATURES**

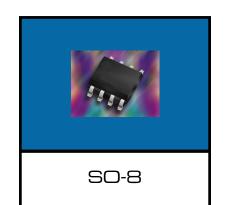
- ✓ 500 Watts Peak Pulse Power Dissipation(t<sub>a</sub> = 8/20µs)
- ✓ Bidirectional Configuration
- ✓ Available in 3.3V & 5V
- ✔ Protects Up to Six (6) I/O Ports
- ✓ ESD Protection > 40 kilovolts
- **✓ LOW CAPACITANCE-15pF**

#### **MECHANICAL CHARACTERISTICS**

- ✓ Molded JEDEC SO-8
- ✓ Weight 15 milligrams (Approximate)
- ✓ Flammability Rating UL 94V-0
- ✓ 12mm Tape and Reel Per EIA Standard 481-1-A
- ✓ Device Marking Code & Logo
- ✔ Pin 1 Indicated By Dot on Package

#### **CIRCUIT DIAGRAM**





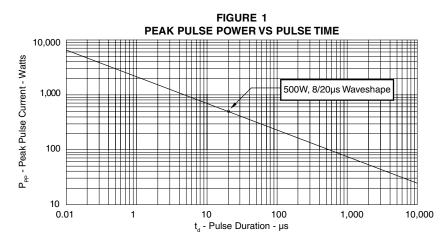
## **DEVICE CHARACTERISTICS**

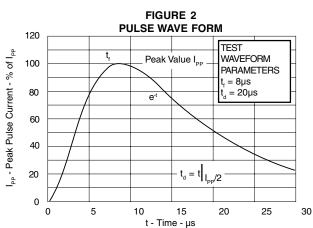
MAXIMUM RATINGS @ 25°C Unless Otherwise Specified							
PARAMETER	SYMBOL	VALUE	UNITS				
Operating Temperature	T <sub>J</sub>	-55°C to 150°C	°C				
Storage Temperature	T <sub>STG</sub>	-55°C to 150°C	°C				
Maximum Forward Voltage @ 100 mA (See Note 1)	V <sub>F</sub>	1.1	Volts				

**Note 1:** Measured between pins 8 to 1, 2, 3, 4, 5, 6, or 7.

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified							
PART NUMBER (See Note 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE	MINIMUM BREAKDOWN VOLTAGE	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM CLAMPING VOLTAGE (See Fig. 2)	MAXIMUM LEAKAGE CURRENT	MAXIMUM CAPACITANCE (See Note 2) (See Figure 5)
		V <sub>wM</sub> VOLTS	@ 1mA V <sub>(BR)</sub> VOLTS	@ I <sub>P</sub> = 1A V <sub>C</sub> VOLTS	@ 8/20µs V <sub>с</sub> @ I <sub>PP</sub>	@ V <sub>wм</sub> Ι <sub>D</sub> μΑ	0V @ 1 MHz C pF
PSRDA3.3-6 PSRDA05-6	SGG SGH	3.3 5.0	4.0 6.0	6.5 9.8	10.9V @ 43.0A 13.5V @ 42.0A		15 15

**Note 1:** Spice model and parameters for this series are available on the ProTek Devices web site: <a href="www.protekdevices.com">www.protekdevices.com</a>. **Note 2:** Capacitance measured at  $V_{WM} = V_{CC}$  connected between I/O pins to pin 8(Gnd).  $V_R = V_{WM}$  @ 1MHz. As shown in Figure 5, REF1 is connected to ground, REF2 is connected to + $V_{CC}$ , and input applies to  $V_{CC} = 5V$ ,  $V_{sign} = mV$ , F = 1 MHz.





## **GRAPHS**

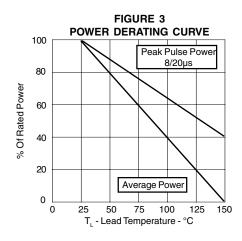


FIGURE 4
OVERSHOOT & CLAMPING VOLTAGE FOR PSRDA05-6

40

40

20

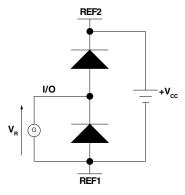
20

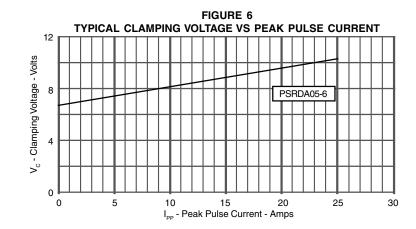
-250.00 ns

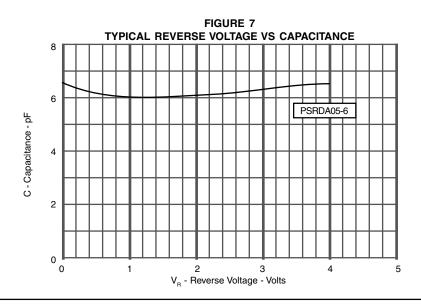
50.0 ns/div

ESD Test Pulse: 8 kilovolt, 1/30ns (waveshape)

# FIGURE 5 INPUT CAPACITANCE CIRCUIT







## APPLICATION NOTE

The PSRDAxx-6 Series are low capacitance, bidirectional TVS arrays that are designed to protect I/O or high speed data lines from the damaging effects of ESD or EFT. This product series has a surge capability of 500 Watts  $P_{pp}$  per line for an 8/20 $\mu$ s waveshape and offers ESD protection > 40 $\mu$ v.

#### **DIFFERENTIAL MODE CONFIGURATION (Figure 1)**

Ideal for use in USB applications, the PSRDAxx-6 Series provides up to six (6) lines of protection in a differential mode configuration as depicted in Figure 1.

Circuit connectivity is as follows:

- ✓ Pins 1, 2, 4, 5, 6 and 7 are connected to the datalines.
- ✔ Pin 8 is connected to ground.
- ✔ Pin 3 is connected to the databus.

#### CIRCUIT BOARD LAYOUT RECOMMENDATIONS

Circuit board layout is critical for Electromagnetic Compatibility (EMC) protection. The following guidelines are recommended:

- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

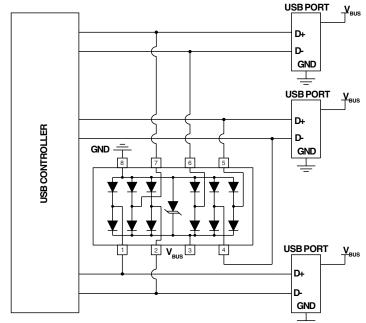
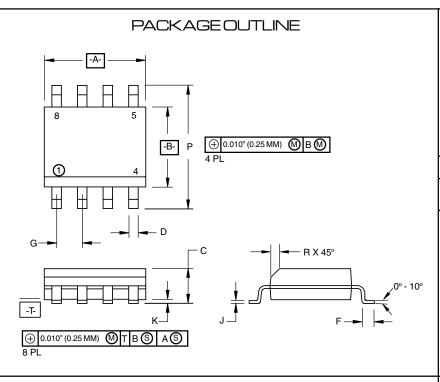


Figure 1. Typical Differential-Mode USB Protection

## PACKAGE OUTLINE & DIMENSIONS



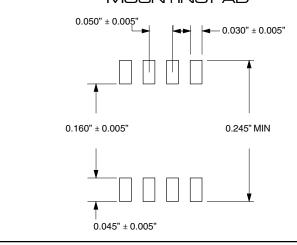
SO-8



#### **PACKAGE DIMENSIONS**

	MILLIME	ETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.196	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.250	0.016	0.049	
G	1.27 BSC	1.27 BSC	0.05 BSC	0.05 BSC	
J	0.18	0.25	0.007	0.009	
K	0.10	0.25	0.004	0.008	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

#### MOUNTINGPAD



#### NOTES

- 1. T = Seating Plane and Datum Surface.
- 2. Dimensions "A" and "B" are Datum.
- 3. Dimensions "A" and "B" do not include mold protrusion.
- Maximum mold protrusion is 0.015" (0.380 mm) per side.
- 5. Dimensioning and tolerances per ANSI Y14.5M, 1982.
- Dimensions are exclusive of mold flash and metal burrs.

06009 Rev 1 -11/01

#### **TAPE & REEL PACKAGING:**

Surface mount product is taped and reeled in accordance with EIA-481, reel quantites and sizes are as follows:

7 Inch Reel - 1,000 pieces per reel; 13 Inch Reel - 2,500 pieces per reel

### ProTek Devices

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